Electronics Packaging Forum Multichip Module Technology Issues

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Lau Puwei Huang John Lau John H. Lau John H. Lau Great Britain. Patent Office Rose Arny John H. Lau Philip E. Garrou Mohamed S. El-Genk IEEE Institute of Electrical and Electronics Engineers

important topics covered include building long term reliability by increasing polyimide stability recent discoveries in the field of soldering phenomena relating to fundamental fluid mechanical processes circuit and electromagnetic solutions to problems of modeling highspeed electrical interconnections how to use the finite difference time domain approach in electromagnetic modeling and the development of dedicated test chips for package evaluation in varied field conditions

a comprehensive guide to tsv and other enabling technologies for 3d integration written by an expert with more than 30 years of experience in the electronics industry through silicon vias for 3d integration provides cutting edge information on tsv wafer thinning thin wafer handling microbumping and assembly and thermal management technologies applications to highperformance high density low power consumption wide bandwidth and small form factor electronic products are discussed this book offers a timely summary of progress in all aspects of this fascinating field for professionals active in 3d integration research and development those who wish to master 3d integration problem solving methods and anyone in need of a low power wide bandwidth design and high yield manufacturing process for interconnect systems coverage includes nanotechnology and 3d integration for the semiconductor industry tsv etching dielectric barrier and seed layer deposition cu plating cmp and cu revealing tsvs mechanical thermal and electrical behaviors thin wafer strength measurement wafer thinning and thin wafer handling microbumping assembly and reliability microbump electromigration transient liquid phase bonding c2c c2w and w2w 2 5d ic integration with interposers 3d ic integration with interposers thermal management of 3d ic integration 3d ic packaging a world list of books in the english language

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